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UCS1001-3 UCS1001-4

USB Port Power Controller with Charger Emulation

PRODUCT FEATURES

Datasheet

General Description

The UCS1001 provides a USB port power switch for precise control of up to 2.5 amperes continuous current with over-current limit (OCL), dynamic thermal management, latch or auto-recovery (low test current) fault handling, selectable active low or high enable, under- and over-voltage lockout, back-drive protection, and back-voltage protection.

Split supply support for VS and VDD is an option for low power in system standby states. This gives battery operated applications, like notebook PCs, the ability to detect attachments from a sleep or off state. After the Attach Detection is flagged, the system can decide to wake up and/or provide charging.

In addition to power switching and current limiting modes, the UCS1001 will automatically charge a wide variety of portable devices, including USB-IF BC1.2, YD/T-1591 (2009), most Apple[®] and RIM[®], and many others. Nine preloaded charger emulation profiles maximize compatibility coverage of peripheral devices.

The UCS1001 is available in a 20-pin QFN 4 mm x 4 mm package.

Applications

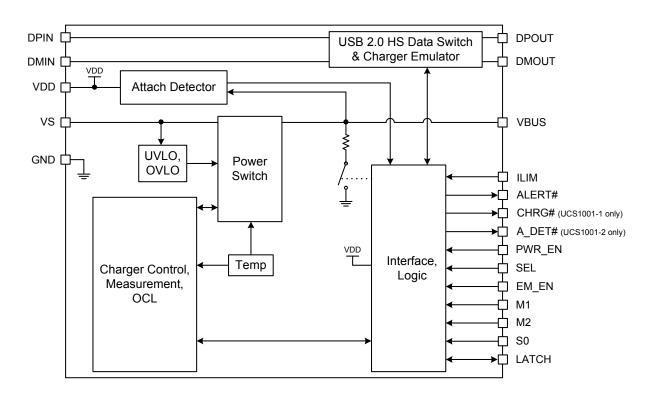
- Notebook and Netbook Computers
- Tablets and E-book readers
- Desktops and Monitors
- Docking Stations and Printers
- AC-DC wall adapters

Features

- Port power switch with two current limit behaviors
 - 2.9 V to 5.5 V source voltage range
 - Up to 2.5 A current with 55 mΩ On Resistance
 - Over-current trip or constant current limiting
 - Soft turn-on circuitry
 - Selectable current limit
 - Dynamic thermal management
 - Under- and over-voltage lockout
 - Back-drive, back-voltage protection
 - Latch or auto-recovery (low test current) fault handling
 - Selectable active high or low power switch enable
 - BC1.2 VBUS discharge port renegotiation function
- Selectable / automatic cycling of USB data line charger emulation profiles
 - Employs unique method and system for sampling multiple profiles*
 - UCS1001-3 and UCS1001-4 supports 12W charger emulation
 - Allows for active cables
 - USB-IF BC1.2 charging downstream port (CDP) & dedicated charging port (DCP) modes, YD/T-1591, and most Apple and RIM protocols standard
 - USB 2.0 compliant high-speed data switch (in Passthrough and CDP modes)
 - Nine preloaded charger emulation profiles for maximum compatibility coverage of peripheral devices
- Charging Active (UCS1001-3) or Attach Detection (UCS1001-4) open-drain output
- Ultra low power Sleep state
- Optional split supply support for VBUS and VDD for low power in system standby states
- Wake on Attach USB (UCS1001-4)
- Wide operating temperature range: -40 °C to +85 °C
- IEC61000-4-2 8 / 15 kV ESD immunity
- UL recognized and EN/IEC 60950-1 (CB) certified

^{*} Unique technology covered under the following US patents pending: 13/109,446; 13/149,529; 13/173,287; 13/233,949; 13/157,282; 12/978,371; 13/232,965.

Block Diagram



ORDERING INFORMATION:

ORDERING NUMBER	PACKAGE	FEATURES
UCS1001-3-BP-TR	20 pin QFN 4mm x 4mm (RoHS compliant)	USB Port Power Controller with Charger Emulation, 12W Emulation support, and charging active output indicator
UCS1001-4-BP-TR	20 pin QFN 4mm x 4mm (RoHS compliant)	USB Port Power Controller with Charger Emulation, 12W Emulation support, and portable device attachment detected output indicator

REEL SIZE IS 4,000 PIECES

This product meets the halogen maximum concentration values per IEC61249-2-21 For RoHS compliance and environmental information, please visit www.smsc.com/rohs

Please contact your SMSC sales representative for additional documentation related to this product such as application notes, anomaly sheets, and design guidelines.

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Chapter 1 Terms and Abbreviations

APPLICATION NOTE: The M1, M2, PWR_EN, and EM_EN pins are referenced in text as the <pin name> control.

Table 1.1 Terms and Abbreviations

TERM / ABBREVIATION	DESCRIPTION
Active mode	Active power state operation mode: Data Pass-through, BC1.2 SDP, BC1.2 CDP, BC1.2 DCP, or Dedicated Charger Emulation Cycle.
attachment	The physical insertion of a portable device into a USB port that UCS1001 is controlling.
CC	Constant current
CDM	Charged Device Model. JEDEC model for characterizing susceptibility of a device to damage from ESD.
CDP or USB-IF BC1.2 CDP	Charging downstream port. The combination of the UCS1001 CDP handshake and an active standard USB host comprises a CDP. This enables a BC1.2 compliant portable device to simultaneously draw current up to 1.5 A while data communication is active. The USB high-speed data switch is closed in this mode.
charge enable	When a charger emulation profile has been accepted by a portable device and charging commences.
charger emulation profile	Representation of a charger comprised of DPOUT, DMOUT, and VBUS signalling which make up a defined set of signatures or handshaking protocols.
connection	USB-IF term which refers to establishing active USB communications between a USB host and a USB device.
current limiting mode	Determines the action that is performed when the IBUS current reaches the ILIM threshold. Trip opens the port power switch. Constant current (variable slope) allows VBUS to be dropped by the portable device.
DCE	Dedicated charger emulation. Charger emulation in which the UCS1001 can deliver power only. No active USB data communication is possible when charging in this mode.
DCP or USB-IF BC1.2 DCP	Dedicated Charging Port. This functions as a dedicated charger for a BC1.2 portable device. This allows the portable device to draw currents up to 1.5 A with constant current limiting (and beyond 1.5 A with trip current limiting). No USB communications are possible.
DC	Dedicated charger. A charger which inherently does not have USB communications, such as an A/C wall adapter.
disconnection	USB-IF term which refers to the loss of active USB communications between a USB host and a USB device.
dynamic thermal management	The UCS1001 automatically adjusts port power switch limits and modes to lower internal power dissipation when the thermal regulation temperature value is approached.
enumeration	A USB-specific term that indicates that a host is detecting and identifying USB devices.
handshake	Application of a charger emulation profile that requires a response. Two-way communication between the UCS1001 and the portable device.
НВМ	Human Body Model.
HSW	High-speed switch.

Table 1.1 Terms and Abbreviations (continued)

TERM / ABBREVIATION	DESCRIPTION			
I _{BUS_R2MIN}	Current limiter mode boundary.			
ILIM	The IBUS current threshold used in current limiting. In trip mode, when ILIM is reached, the port power switch is opened. In constant current mode, when the current exceeds ILIM, operation continues at a reduced voltage and increased current; if VBUS voltage drops below $V_{\text{BUS_MIN}}$, the port power switch is opened.			
Legacy	USB devices that require non-BC1.2 signatures be applied on the DPOUT and DMOUT pins to enable charging.			
OCL	Over-current limit.			
portable device	USB device attached to the USB port.			
power thief	A USB device that does not follow the handshaking conventions of a BC1.2 device or Legacy devices and draws current immediately upon receiving power (i.e., a USB book light, portable fan, etc).			
removal	The physical removal of a portable device from a USB port that the UCS1001 is controlling.			
SDP or USB-IF SDP	Standard downstream port. The combination of the UCS1001 high-speed switch being closed with an upstream USB host present comprises a BC1.2 SDP. This enables a BC1.2 compliant portable device to simultaneously draw current up to 0.5 A while data communication is active.			
signature	Application of a charger emulation profile without waiting for a response. One-way communication from the UCS1001 to the portable device.			

Chapter 2 Pin Description

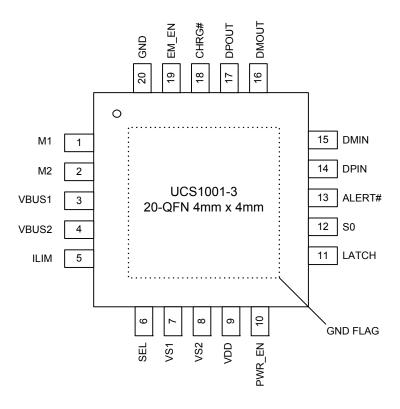


Figure 2.1 UCS1001-3 Pin Diagram

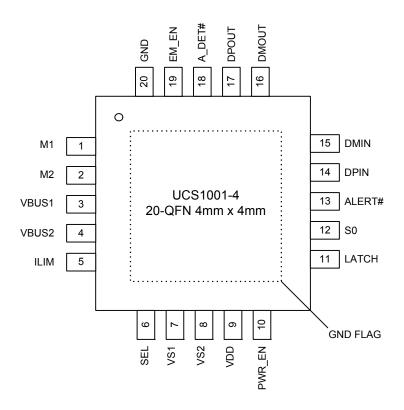


Figure 2.2 UCS1001-4 Pin Diagram

The pin types are described in Table 2.2. All pins are 5 V tolerant.

Table 2.1 UCS1001 Pin Description

PIN NUMBER	PIN NAME	PIN FUNCTION	PIN TYPE	IF PIN NOT USED CONNECTION
1	M1	Active mode selector input #1	DI	Connect to ground or VDD (see Note 2.2)
2	M2	Active mode selector input #2	DI	Connect to ground or VDD (see Note 2.2)
3	VBUS1	Voltage output from Power Switch.	Hi-Power, AIO	Leave open
4	VBUS2	These pins must be tied together.	Note 2.1	
5	ILIM	Selects the maximum current limit at power-up	AIO	n/a
6	SEL	Selects polarity of PWR_EN control	DI	n/a
7	VS1	Voltage input to Power Switch. These pins must be tied together.	Hi-Power, AIO	Connect to ground
8	VS2	These pins must be tied together.	AIO	

Table 2.1 UCS1001 Pin Description (continued)

PIN NUMBER	PIN NAME	PIN FUNCTION PIN TYP		IF PIN NOT USED CONNECTION
9	VDD	Main power supply input for chip Power functionality		n/a
10	PWR_EN	Port power switch enable input. Polarity determined by SEL pin.	DI	Connect to ground or VDD (see Note 2.2)
11	LATCH	Latch / Auto-recovery fault handling mechanism selection input	DI	n/a
12	S0	Enables Attach / Removal Detection feature	DI	n/a
13	ALERT#	Active low error event output flag (requires pull-up resistor)	OD	Connect to ground
14	DPIN	USB data input (plus)	AIO	Connect to ground or ground through a resistor
15	DMIN	USB data input (minus)	AIO	Connect to ground or ground through a resistor
16	DMOUT	USB data output (minus)	AIO	Connect to ground
17	DPOUT	USB data output (plus)	AIO	Connect to ground
18 (UCS1001-1, UCS1001-3)	CHRG#	Active low "Charging Active" output flag (requires pull-up resistor)	OD	Connect to ground
18 (UCS1001-2, UCS1001-4)	A_DET#	Active low Attach Detection output flag (requires pull-up resistor)		Connect to ground
19	EM_EN	Active mode selector input DI		Connect to ground or VDD (see Note 2.2)
20	GND	Ground	Power	n/a
Bottom Pad	GND FLAG	Thermal connection to ground plane Thermal Pad		n/a

- Note 2.1 Total leakage current from pins 3 and 4 (VBUS) to ground must be less than 100 μ A for proper attach / removal detection operation.
- Note 2.2 To ensure operation, the PWR_EN pin must be enabled, as determined by the SEL pin decode, when it is not driven by an external device. Furthermore, one of the M1, M2, or EM_EN pins must be connected to VDD if all three are not driven from an external device. If the PWR_EN is disabled or all of the M1, M2, and EM_EN are connected to ground, the UCS1001 will remain in the Sleep or Detect state indefinitely.

Table 2.2 Pin Types

PIN TYPE	DESCRIPTION		
Power	This pin is used to supply power or ground to the device.		
Hi-Power	This pin is a high current pin.		
AIO	Analog Input / Output - this pin is used as an I/O for analog signals.		
DI	Digital Input - this pin is used as a digital input.		
OD	Open-drain Digital Output - used as a digital output. It is open-drain and requires a pull-up resistor.		

Chapter 3 Electrical Specifications

Table 3.1 Absolute Maximum Ratings

Voltage on VDD, VS, and VBUS pins	-0.3 to 6	V
Pullup voltage (V _{PULLUP})	-0.3 to VDD + 0.3	
Data switch current (I _{HSW_ON}), switch on	±50	mA
Port power switch current	Internally limited	
Data switch pin voltage to ground (DPOUT, DPIN, DMOUT, DMIN); (VDD powered or unpowered)	-0.3 to VDD + 0.3	V
Differential voltage across open data switch (DPOUT - DPIN, DMOUT - DMIN, DPIN - DPOUT, DMIN - DMOUT)	VDD	V
Voltage on any other pin to ground	-0.3 to VDD + 0.3	V
Current on any other pin	±10	mA
Package power dissipation	See Table 3.2	
Operating ambient temperature range	-40 to 125	°C
Storage temperature range	-55 to 150	°C

Note: Stresses above those listed could cause permanent damage to the UCS1001. This is a stress rating only and functional operation of the UCS1001 at any other condition above those indicated in the operation sections of this specification is not implied.

Table 3.2 Power Dissipation Summary

BOARD	PKG	$\theta_{ extsf{JC}}$	$\theta_{\sf JA}$	DERATING FACTOR ABOVE 25 °C	TA < 25°C POWER RATING	TA = 70 °C POWER RATING	TA = 85 °C POWER RATING
High K (see Note 3.1)	20-pin QFN 4 mm x 4 mm	6 °C /	41 °C / W	24.4 mW / °C	2193 mW	1095 mW	729 mW
Low K (see Note 3.1)	20-pin QFN 4 mm x 4 mm	6 °C / W	60 °C / W	16.67 mW / °C	1498 mW	748 mW	498 mW

Note 3.1 A High K board uses a thermal via design with the thermal landing soldered to the PCB ground plane with 0.3 mm (12 mil) diameter vias in a 3x3 matrix (9 total) at 0.5 mm (20 mil) pitch. The board is multi-layer with 1-ounce internal power and ground planes and 2-ounce copper traces on top and bottom. A Low K board is a two layer board without thermal via design with 2-ounce copper traces on the top and bottom.

Table 3.3 Electrical Specifications

VDD = 4 all Ty	1.5 V to 5.5 V, VS pical values at VD	= 2.9 V t	o 5.5 V, V _I = 5 V, T _A =	OULLUP = 3 = 27 °C ur	3 V to 5.5 less othe	V, = -40 °C to rwise noted.		
CHARACTERISTIC	SYMBOL	MIN	TYP	MAX	UNIT	CONDITIONS		
Power and Interrupts - DC								
Supply Voltage	VDD	4.5	5	5.5	V	See Note 3.2		
Source Voltage	VS	2.9	5	5.5	V	See Note 3.2		
Supply Current in Active (I _{DD_ACTIVE} + I _{VS_ACT})	I _{ACTIVE}		650	750	μΑ	Average current IBUS = 0 mA		
Supply Current in Sleep (I _{DD_SLEEP} + I _{VS_SLEEP})	I _{SLEEP}		5	15	μА	Average current V _{PULLUP} ≤ VDD		
Supply Current in Detect (IDD_DETECT + IVS_DETECT)	I _{DETECT}		185	220	μА	Average current No portable device attached.		
Power-on Reset								
VS Low Threshold	V _{S_UVLO}		2.5		V	VS voltage increasing		
VS Low Hysteresis	V _{S_UVLO_HYST}		100		mV	VS voltage decreasing		
VDD Low Threshold	V _{DD_TH}		4		V	VDD voltage increasing		
VDD Low Hysteresis	V _{DD_TH_HYST}		500		mV	VDD voltage decreasing		
I/O Pins - EM_EN, M1,	M2, PWR_EN, AL	ERT#, C	HRG# (UC	S1001-3),	A_DET#	(UCS1001-4)- DC Parameters		
Output Low Voltage	V _{OL}			0.4	V	I _{SINK_IO} = 8 mA ALERT#CHRG#, A_DET#		
Input High Voltage	V _{IH}	2.0			V	PWR_EN, EM_EN, M1, M2		
Input Low Voltage	V _{IL}			0.8	V	PWR_EN, EM_EN, M1, M2, EM_EN		
Leakage Current	I _{LEAK}			±5	μΑ	Powered or unpowered $V_{PULLUP} \le VDD$ $T_A \le 85 °C$		
	In	terrupt Pi	ns - AC P	arameters				
ALERT#, A_DET# Pin Blanking Time	t _{BLANK}		25		ms			
ALERT# Pin Interrupt Masking Time	t _{MASK}		5		ms			
		High-sp	eed Data	Switch				
	High-sp	eed Data	Switch -	DC Paran	neters			

Table 3.3 Electrical Specifications (continued)

VDD = 4.5 V to 5.5 V, VS = 2.9 V to 5.5 V, V_{PULLUP} = 3 V to 5.5 V, = -40 °C to all Typical values at VDD = VS = 5 V, T_A = 27 °C unless otherwise noted. UNIT **CHARACTERISTIC SYMBOL** MIN **TYP** MAX **CONDITIONS** Switch open - DPIN to DPOUT, Switch Leakage Current ±0.5 μΑ I_{HSW_OFF} DMIN to DMOUT, or all four pins to ground. $VDD \leq VS$. DPOUT or DMOUT to VBUS or Charger Resistance 2 $M\Omega$ R_{CHG} ground, see Figure 3.2 BC1.2 DCP charger emulation active Switch closed, VDD = 5 V On Resistance 2 Ω R_{ON HSW} test current = 8 mA, test voltage = 0.4 V, see Figure 3.2 Switch closed, VDD = 5 V, On Resistance 5 Ω R_{ON_HSW_1} test current = 8 mA, test voltage = 3.0 V, see Figure 3.2 Delta On Resistance ΔR_{ON_HSW} ±0.3 Ω Switch closed, VDD = 5 V I_{TST} = 8 mA, V_{TST} = 0 to 1.5 V, see Figure 3.2 High-speed Data Switch - AC Parameters DP, DM Capacitance to Switch closed C_{HSW_ON} Ground VDD = 5 VDP, DM Capacitance to C_{HSW_OFF} 2 pF Switch open Ground VDD = 5VTurn Off Time 400 Time from state control μs t_{HSW_OFF} (EM_EN, M1, M2) switch on to switch off, $R_{TERM} = 50 \Omega$, $C_{LOAD} = 5 pF$ Turn On Time 400 Time from state control μs t_{HSW} ON (EM_EN, M1, M2) switch off to switch on, R_{TERM} = 50 Ω , C_{LOAD} = 5 pF Propagation Delay 0.25 R_{TERM} = 50 Ω , C_{LOAD} = 5 pF t_{PD} ns R_{TERM} = 50 Ω , C_{LOAD} = 5 pF Propagation Delay Skew Δt_{PD} 25 ps Rise/Fall Time R_{TERM} = 50 Ω , C_{LOAD} = 5 pF 10 $t_{F/R}$ ns DP - DM Crosstalk -40 dB R_{TERM} = 50 Ω , C_{LOAD} = 5 pF X_{TALK} R_{TERM} = 50 Ω , C_{LOAD} = 5 pF f = 240 MHz Off Isolation -30 dB O_{IRR} R_{TERM} = 50 Ω , C_{LOAD} = 1.5 pF V_{DPOUT} = V_{DMOUT} = 350 mV DC-3dB Bandwidth BW 1100 MHz

of unpowered pin.

Table 3.3 Electrical Specifications (continued)

	Table 3.3	Electrica	I Specifica	ations (co	ntinued)	
VDD = 4 all Typ	.5 V to 5.5 V, VS pical values at V	S = 2.9 V t DD = VS	o 5.5 V, V _I = 5 V, T _A =	PULLUP = 3 = 27 °C un	3 V to 5.5 less othe	V, = -40 °C to erwise noted.
CHARACTERISTIC	SYMBOL	MIN	TYP	MAX	UNIT	CONDITIONS
Total Jitter	tu		200		ps	R_{TERM} = 50 Ω , C_{LOAD} = 5 pF, rise time = fall time = 500 ps at 480 Mbps (PRBS = 2^{15} - 1)
Skew of Opposite Transitions of the Same Output	t _{SK(P)}		20		ps	$R_{TERM} = 50 \Omega$, $C_{LOAD} = 5 pF$
		Port	Power Sv	vitch		
	Ро	rt Power S	Switch - Do	C Paramet	er	
Over-voltage Lockout	V _{S_OV}		6		V	
On Resistance	R _{ON_PSW}		55	65	mΩ	4.75 V < VS < 5.25 V
VS Leakage Current	I _{LEAK_VS}		2.2	5	μA	Sleep state into VS pin
Back-voltage Protection Threshold	V _{BV_TH}		150		mV	VBUS > VS VS > V _{S_UVLO}
Back-drive Current	I _{BD_1}		0	3	μА	VDD < V _{DD_TH} , Any powered power pin to any unpowered power pin. Current out of unpowered pin.
	I _{BD_2}		0	2	μA	VDD > V _{DD TH} , Any powered power pin to any unpowered power pin, except for VDD to VBUS in Detect power state and VS to VBUS in Active power state. Current out

Table 3.3 Electrical Specifications (continued)

VDD = 4.5 V to 5.5 V, VS = 2.9 V to 5.5 V, V_{PULLUP} = 3 V to 5.5 V, = -40 °C to all Typical values at VDD = VS = 5 V, T_{Δ} = 27 °C unless otherwise noted.

CHARACTERISTIC	SYMBOL	MIN	TYP	MAX	UNIT	CONDITIONS
Selectable Current Limits	I _{LIM1}		480	500	mA	ILIM Resistor = 47 kΩ (500 mA setting)
	I _{LIM2}		850	900	mA	ILIM Resistor = 56 kΩ (900 mA setting)
	I _{LIM3}		950	1000	mA	ILIM Resistor = 68 kΩ (1000 mA setting)
	I _{LIM4}		1130	1200	mA	ILIM Resistor = 82 kΩ (1200 mA setting)
	I _{LIM5}		1400	1500	mA	ILIM Resistor = 100 kΩ (1500 mA setting)
	I _{LIM6}		1720	1800	mA	ILIM Resistor = 120 kΩ (1800 mA setting)
	I _{LIM7}		1910	2000	mA	ILIM Resistor = 150 kΩ (2000 mA setting)
	I _{LIM8}		2370	2500	mA	ILIM Resistor = VDD (2500 mA setting)
Pin Wake Time	t _{PIN_WAKE}		3		ms	
Thermal Regulation Limit	T _{REG}		110		°C	Die Temperature at which current limit will be reduced
Thermal Regulation Hysteresis	T _{REG_HYST}		10		°C	Hysteresis for t _{REG} functionality. Temperature must drop by this value before ILIM value restored to normal operation
Thermal Shutdown Threshold	T _{TSD}		135		°C	Die Temperature at which port power switch will turn off
Thermal Shutdown Hysteresis	T _{TSD_HYST}		35		°C	After shutdown due to T _{TSD} being reached, die temperature drop required before port power switch can be turned on again
Auto-recovery Test Current	I _{TEST}		190		mA	Portable device attached, VBUS = 0 V, Die temp < T _{TSD}
Auto-recovery Test Voltage	V _{TEST}		750		mV	Portable device attached, VBUS = 0 V before application, Die temp < T _{TSD}
Discharge Impedance	R _{DISCHARGE}	100			Ω	

Table 3.3 Electrical Specifications (continued)

	Table 3.3 i	Liectrica	Specifica	itions (co	nunueu)			
VDD = 4.5 V to 5.5 V, VS = 2.9 V to 5.5 V, V_{PULLUP} = 3 V to 5.5 V, = -40 °C to all Typical values at VDD = VS = 5 V, T_A = 27 °C unless otherwise noted.								
CHARACTERISTIC	SYMBOL	MIN	TYP	MAX	UNIT	CONDITIONS		
	Port	Power S	witch - AC	Paramete	ers			
Turn On Delay	t _{ON_PSW}		0.75		ms	PWR_EN active toggle to switch on time, VBUS discharge not active		
Turn Off Time	toff_psw_ina		0.75		ms	PWR_EN inactive toggle to switch off time C _{BUS} = 120 μF		
Turn Off Time	toff_psw_err		1		ms	Over-current Error, VBUS Min Error, or Discharge Error to switch off C _{BUS} = 120 µF		
Turn Off Time	t _{OFF_PSW_ERR}		100		ns	TSD or Back-drive Error to switch off C _{BUS} = 120 μF		
VBUS Output Rise Time	^t R_BUS		1.1		ms	Measured from 10% to 90% of VBUS, C_{LOAD} = 220 μ F ILIM = 1.0 A		
Soft Turn on Rate	Δl _{BUS} / Δ _t		100		mA / μs			
Temperature Update Time	t _{DC_TEMP}		200		ms			
Short Circuit Response Time	^t SHORT_LIM		1.5		μs	Time from detection of short to current limit applied. No C _{BUS} applied		
Short Circuit Detection Time	t _{SHORT}		6		ms	Time from detection of short to port power switch disconnect and ALERT# pin assertion.		
Latched Mode Cycle Time	t _{UL}		7		ms	From PWR_EN edge transition from inactive to active to begin error recovery		
Auto-recovery Mode Cycle Time	t _{CYCLE}		25		ms	Time delay before error condition check		
Auto-recovery Delay	t _{RST}		20		ms	Portable device attached, VBUS must be ≥ V _{TEST} after this time		
Discharge Time	t _{DISCHARGE}		200		ms	Amount of time discharge resistor applied		

Table 3.3 Electrical Specifications (continued)

VDD = 4.5 V to 5.5 V, VS = 2.9 V to 5.5 V, V_{PULLUP} = 3 V to 5.5 V, = -40 °C to all Typical values at VDD = VS = 5 V, T_A = 27 °C unless otherwise noted.								
CHARACTERISTIC	SYMBOL	MIN	TYP	MAX	UNIT	CONDITIONS		
Port Power Switch Operation With Trip Mode Current Limiting								
Region 2 Current Keep- out	I _{BUS_R2MIN}			0.1	А			
Minimum VBUS Allowed at Output	V _{BUS_MIN}	2.0			V			
Port Po	ower Switch Opera	ation Witl	h Constant	Current L	imiting (\	/ariable Slope)		
Region 2 Current Keep- out	I _{BUS_R2MIN}			1.5	А			
Minimum VBUS Allowed at Output	V _{BUS_MIN}	2.0			V			
	VBUS Bypass - DC							
On Resistance	R _{ON_BYP}		50		Ω			
Leakage Current	I _{LEAK_BYP}			3	μA	Switch off		
Current Limit	I _{DET_CHG} / I _{BUS_BYP}		2		mA	VDD = 5 V and VBUS> 4.75 V		
	Att	ach / Rei	moval Dete	ection - DO				
Attach Detection Threshold	I _{DET_QUAL}		800		μA			
Primary Removal Detection Threshold	I _{REM_QUAL_ACT}		700		μA	Active power state		
	I _{REM_QUAL_DET}		800		μA	Detect power state (see Section 7.4)		
Attach / Removal Detection - AC								
Attach Detection Time	t _{DET_QUAL}		100		ms	Time from Attach to A_DET# assert (UCS1001-4 only).		
Removal Detection Time	t _{REM_QUAL}		1000		ms			
Allowed Charge Time	t _{DET_CHARGE}		800		ms	C _{BUS} = 500 μF max		
		Charger	Emulation	Profile				
		Genera	I Emulation	n - DC				
Charging Current Threshold	I _{BUS_CHG}		156		mA			

Table 3.3 Electrical Specifications (continued)

VDD = 4.5 V to 5.5 V, VS = 2.9 V to 5.5 V, V_{PULLUP} = 3 V to 5.5 V, = -40 °C to all Typical values at VDD = VS = 5 V, T_A = 27 °C unless otherwise noted.							
CHARACTERISTIC	SYMBOL	MIN	TYP	MAX	UNIT	CONDITIONS	
DP-DM Shunt Resistor Value	R _{DCP_RES}			200	Ω	Connected between DPOUT and DMOUT 0 V < DPOUT = DMOUT ≤ 3 V	
Voltage Output	SX_RXMAG_ VOLT_BC	0.5			V	DMOUT 250 μA load	
Pull-down Current	SX_PUPD _ACC_BC	50			μΑ	DPOUT or DMOUT = 0.15 V Compliance voltage	
General Emulation - AC							
Emulation Reset Time	t _{EM_RESET}		50		ms		

Note 3.2 For split supply systems using the Attach Detection feature, VS must not exceed VDD + 150 mV.

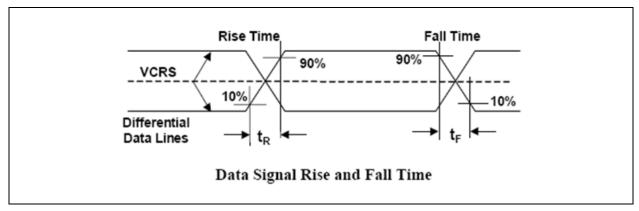


Figure 3.1 USB Rise Time / Fall Time Measurement

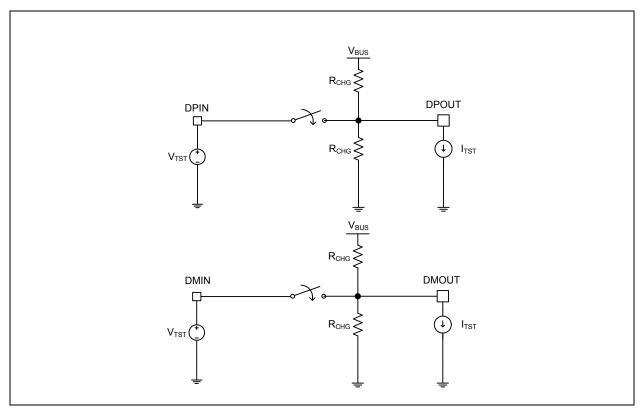


Figure 3.2 Description of DC Terms

3.1 **ESD & Transient Performance**

APPLICATION NOTE: Depending on the level of ESD protection required by the application, external protection devices may be required. The datasheet ESD levels were reached using external devices and standard USB-A connectors; refer to the EVB schematic and reference design for details.

Table 3.4 ESD Ratings

ESD SPEC	RATING OR VALUE
EN / IEC61000-4-2 (DPOUT, DMOUT pins) air gap, Operational Classification B (see Note 3.3)	Level4(15kV)
EN / IEC61000-4-2 (DPOUT, DMOUT pins) direct contact, Operational Classification B (see Note 3.3)	Level4(8 kV)
EN / IEC61000-4-2 (VBUS, GND pins) air gap, Operational Classification A (see Note 3.4)	Level4(15 kV)
EN / IEC61000-4-2 (VBUS, GND pins) direct contact, Operational Classification A (see Note 3.4)	Level4(8 kV)

- Note 3.3 Operational Classification B indicates that during and immediately after an ESD event, anomalous behavior may occur; however, it is non-damaging and the device is selfrecovering. All IEC testing is performed using an SMSC evaluation board.
- Note 3.4 Operational Classification A indicates that during and immediately after an ESD event no anomalous behavior will occur. All IEC testing is performed using an SMSC evaluation board.

3.1.1 **Human Body Model (HBM) Performance**

HBM testing verifies the ability to withstand ESD strikes like those that occur during handling and manufacturing and is done without power applied to the IC. To pass the test, the device must have no change in operation or performance due to the event.

3.1.2 **Charged Device Model (CDM) Performance**

CDM testing verifies the ability to withstand ESD strikes like those that occur during handling and assembly with pick and place style machinery and is done without power applied to the IC. To pass the test, the device must have no change in operation or performance due to the event.

3.1.3 IEC61000-4-2 Performance

The IEC61000-4-2 ESD specification is an international standard that addresses system-level immunity to ESD strikes while the end equipment is operational. These tests are performed while the device is powered.

Chapter 4 General Description

The UCS1001 provides a single USB port power switch for precise control of up to 2.5 amperes continuous current with over-current limit (OCL), dynamic thermal management, latch or auto-recovery fault handling, selectable active low or high enable, under- and over-voltage lockout, and back-voltage protection.

Split supply support for VBUS and VDD is an option for low power in system standby states.

In addition to power switching and current limiting, the UCS1001 provides charger emulation profiles to charge a wide variety of portable devices, including USB-IF BC1.2 (CDP or DCP modes), YD/T-1591 (2009), most Apple and RIM portable devices, and many others.

Figure 4.1 shows a system configuration in which the UCS1001-3 provides a port power switch, low power Attach Detection, and charging active signaling. Figure 4.2 shows a system configuration in which the UCS1001-4 provides a port power switch, low power Attach Detection, and portable device Attach Detection signaling. These configurations are useful for applications that already provide USB BC1.2 and/or legacy data line handshaking on the USB data lines, but still require port power switching.

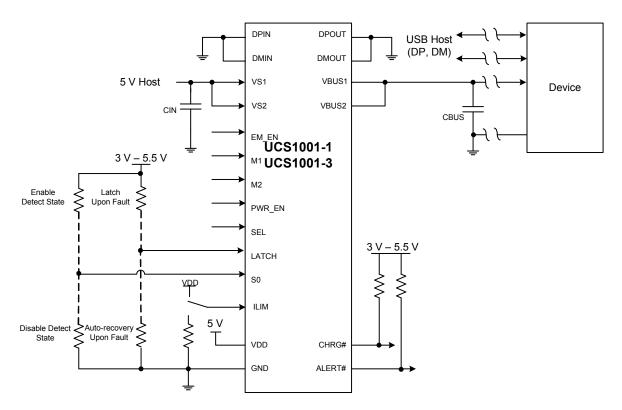


Figure 4.1 UCS1001-3 System Configuration (No Charger Emulation)

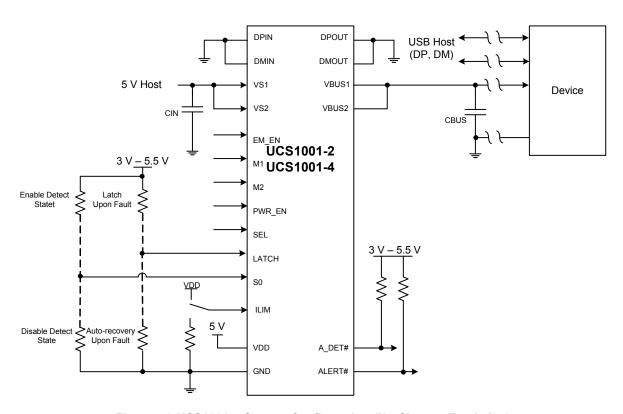


Figure 4.2 UCS1001-4 System Configuration (No Charger Emulation)

Figure 4.3 shows a system configuration in which the UCS1001-3 provides a port power switch, low power Attach Detection, charger emulation (with no USB host), and charging active signaling. Figure 4.4 shows a system configuration in which the UCS1001-4 provides a port power switch, low power Attach Detection, charger emulation (with no USB host), and portable device Attach Detection signaling. These configurations are useful for wall adapter type applications.